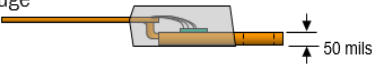




Initial Product/Process Change Notification

Document #: IPCN23071X

Issue Date: 20 May 2020

Title of Change:	ON Semiconductor Seremban, Malaysia qualification of ICD2PAK 5LD single gauge frame and G700HF mold compound.	
Proposed First Ship date:	01 Sep 2020 or earlier if approved by customer.	
Contact Information:	Contact your local ON Semiconductor Sales Office or AhmadFaris.Dzulkipli@onsemi.com , IgnatiusPillay.FelixAmbrose@onsemi.com	
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or PCN.samples@onsemi.com Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact PCN.Support@onsemi.com	
Marking of Parts/ Traceability of Change:	Change material will be identified by encoded date code.	
Change Category:	Assembly Change	
Change Sub-Category(s):	Material Change, Product specific change	
Sites Affected:		
ON Semiconductor Sites	External Foundry/Subcon Sites	
ON Semiconductor Seremban, Malaysia	None	
Description and Purpose:		
Leadframe heatsink thickness change from dual gauge thickness to single gauge thickness 50mils to 20mils and mold compound change from G600 to G700HF.		
	Before Change Description	After Change Description
Lead Frame	<p>Dual gauge thickness</p> <p>Dual Gauge </p>	<p>Single gauge thickness</p> <p>Single Gauge </p>
Mold Compound	G600: Low Adhesion compound	G700HF: High adhesion compound to improve delamination performance

**Qualification Plan:**

QV DEVICE NAME: NCV87722D5S33R4G, NCV59301DS25R4G, MC33167D2TR4G

Package : ICD2PAK 5LD

Test	Specification	Condition	Interval
HAST	JESD22 A110	130°C/85% RH , ~18.8 psig	192 hrs
HTSL	JESD22-A103	Ta = 150 °C	2016 hrs
HTOL	JESD22 A108	TA=125°C	1008 hrs
TC	JESD22-A104	Ta = -65°C to +150°C	500 cyc
AC	JESD22-A102	121°C, 100% RH, 15psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 245 °C	
RSH	JESD22- B106	Ta = 265°C, 10 sec	
SD	JSTD002	Ta = 245°C, 10 sec	

Estimated date for qualification completion: **1 June 2020**

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
MC33166D2TG	MC33167D2TR4G
MC33166D2TR4G	MC33167D2TR4G
NCP59151DS25R4G	NCV59301DS25R4G
NCP59151DS28R4G	NCV59301DS25R4G
NCP59151DS30R4G	NCV59301DS25R4G
NCP59151DS33R4G	NCV59301DS25R4G
NCP59151DS50R4G	NCV59301DS25R4G
NCP59301DS18R4G	NCV59301DS25R4G
NCP59301DS25R4G	NCV59301DS25R4G
NCP59301DS28R4G	NCV59301DS25R4G
LM2575D2T-12R4G	MC33167D2TR4G
LM2575D2T-15R4G	MC33167D2TR4G
LM2575D2T-3.3R4G	MC33167D2TR4G



LM2575D2T-5G	MC33167D2TR4G
LM2575D2T-5R4G	MC33167D2TR4G
LM2575D2T-ADJG	MC33167D2TR4G
LM2575D2T-ADJR4G	MC33167D2TR4G
LM2576D2T-005G	MC33167D2TR4G
LM2576D2T-15G	MC33167D2TR4G
LM2576D2T-ADJG	MC33167D2TR4G
LM2576D2T-ADJR4G	MC33167D2TR4G
LM2576D2TR4-012G	MC33167D2TR4G
LM2576D2TR4-3.3G	MC33167D2TR4G
LM2576D2TR4-5G	MC33167D2TR4G
LM2595DSADJR4G	MC33167D2TR4G
LM2596DSADJG	MC33167D2TR4G
LM2596DSADJR4G	MC33167D2TR4G
MC33167D2TG	MC33167D2TR4G
MC33167D2TR4G	MC33167D2TR4G
MC34166D2TR4G	MC33167D2TR4G
MC34167D2TG	MC33167D2TR4G
MC34167D2TR4G	MC33167D2TR4G
LM2931ACD2TR4G	NCV59301DS25R4G
LM2931CD2TG	NCV59301DS25R4G
LM2931CD2TR4G	NCV59301DS25R4G
NCP565D2TG	NCV59301DS25R4G
NCP565D2TR4G	NCV59301DS25R4G
NCP5662DS12R4G	NCV59301DS25R4G
NCP5662DS15R4G	NCV59301DS25R4G
NCP5662DS18R4G	NCV59301DS25R4G
NCP5662DS25R4G	NCV59301DS25R4G
NCP5662DS28R4G	NCV59301DS25R4G
NCP5662DS30R4G	NCV59301DS25R4G
NCP5662DS33R4G	NCV59301DS25R4G
NCP5662DSADJR4G	NCV59301DS25R4G
NCP5663DS15R4G	NCV59301DS25R4G
NCP5663DS18G	NCV59301DS25R4G



NCP5663DS18R4G	NCV59301DS25R4G
NCP5663DSADJR4G	NCV59301DS25R4G
NCP57152DSADJR4G	NCV59301DS25R4G
NCP57302DSADJR4G	NCV59301DS25R4G
NCP58302DSADJR4G	NCV59301DS25R4G
NCP59301DS30R4G	NCV59301DS25R4G
NCP59301DS33R4G	NCV59301DS25R4G
NCP59301DS50R4G	NCV59301DS25R4G
NCP59302DSADJR4G	NCV59301DS25R4G
NCP630AD2TG	NCV59301DS25R4G
NCP630AD2TR4G	NCV59301DS25R4G
NCP630GD2TG	NCV59301DS25R4G
NCP630GD2TR4G	NCV59301DS25R4G
SCY99302DSADJR4G	NCV59301DS25R4G

Japanese translation of the notification starts here.
通知の日本語訳はここから始まります。

Note: The Japanese version is for reference only. In case of any differences between the English and Japanese version, the English version shall control.


注：日本語版は参照用です。英語版と日本語版の違いがある場合は、英語版が優先されます。



初回製品 / プロセス変更通知

文書番号# : IPCN23071X

発行日: 20 May 2020

変更件名:	オンセミコンダクターセレンバン、マレーシアの ICD2PAK 5LD シングルゲージフレームおよび G700HF モールドコンパウンドの認定	
初回出荷予定日:	01 Sep 202017 or earlier if approved by customer	
連絡先情報:	現地のオン・セミコンダクター営業所または AhmadFaris.Dzulkipli@onsemi.com , IgnatiusPillay.FelixAmbrose@onsemi.com にお問い合わせください。	
サンプル:	現地のオン・セミコンダクター営業所または PCN.samples@onsemi.com にお問い合わせください。サンプルは、この変更の初回通知、初回 PCN の日付から 30 日以内に要求してください。サンプル納入時は、依頼日、数量、特別梱包材/ラベル条件によって異なります。	
通知種別:	これは、お客様宛の初回製品 / プロセス変更通知 (IPCN) です。IPCN は、近日中に実施される変更に関する事前通知であり、変更の詳細および影響を受けるデバイスについての一般情報が記載されます。また、暫定的な信頼性認証計画も記載されます。最終的な認定データおよび特性データは最終製品 / プロセス変更通知 (FPCN) に含まれます。この IPCN は、変更実施から少なくとも 90 日前に発行される最終製品 / プロセス変更通知 (FPCN) に先だって通知されます。ご不明な点がありましたら、 PCN.Support@onsemi.com にお問い合わせください。	
部品のマーキング/変更のトレーサビリティ:	変更材料は、エンコードされた日付コードによって識別されます。	
変更カテゴリ:	アセンブリの変更	
変更サブカテゴリ:	材料の変更, 製品仕様の変更	
影響を受ける拠点:		
オン・セミコンダクター拠点:	外部製造工場 / 下請業者拠点:	
ON Semiconductor Seremban, Malaysia		なし
説明および目的:	リードフレームヒートシンクの厚さがデュアルゲージの厚さ 50 ミルからシングルゲージの厚さ 20 ミルに変更され、モールドコンパウンドが G600 から G700HF に変更されます。	
	変更前の表記	変更後の表記
リードフレーム	デュアルゲージ厚 Dual Gauge 	シングルゲージ厚 Single Gauge 
モールド・コンパウンド	G600: 低接着性コンパウンド	G700HF: 剥離性能を向上させる高接着性コンパウンド



認定計画:

デバイス名: NCV87722D5S33R4G, NCV59301DS25R4G, MC33167D2TR4G

パッケージ: ICD2PAK 5LD

テスト	規格	条件	間隔
HAST	JESD22 A110	130°C/85% RH, ~18.8 psig	192 hrs
HTSL	JESD22-A103	Ta = 150 °C	2016 hrs
HTOL	JESD22 A108	TA=125°C	1008 hrs
TC	JESD22-A104	Ta = -65°C to +150°C	500 cyc
AC	JESD22-A102	121°C, 100% RH, 15psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 245 °C	
RSH	JESD22- B106	Ta = 265°C, 10 sec	
SD	JSTD002	Ta = 245°C, 10 sec	

認定完了予定: 1 June 2020

影響を受ける部品の一覧:

注: 部品一覧には標準部品番号 (既製品) のみが記載されています。本 PCN の影響を受けるカスタム部品番号は、PCN メールで提供される顧客個別の付録、または PCN カスタマイズポータルに記載されています。

部品番号	認定試験用ピークル
MC33166D2TG	MC33167D2TR4G
MC33166D2TR4G	MC33167D2TR4G
NCP59151DS25R4G	NCV59301DS25R4G
NCP59151DS28R4G	NCV59301DS25R4G
NCP59151DS30R4G	NCV59301DS25R4G
NCP59151DS33R4G	NCV59301DS25R4G
NCP59151DS50R4G	NCV59301DS25R4G
NCP59301DS18R4G	NCV59301DS25R4G
NCP59301DS25R4G	NCV59301DS25R4G
NCP59301DS28R4G	NCV59301DS25R4G
LM2575D2T-12R4G	MC33167D2TR4G
LM2575D2T-15R4G	MC33167D2TR4G
LM2575D2T-3.3R4G	MC33167D2TR4G
LM2575D2T-5G	MC33167D2TR4G
LM2575D2T-5R4G	MC33167D2TR4G
LM2575D2T-ADJG	MC33167D2TR4G
LM2575D2T-ADJR4G	MC33167D2TR4G
LM2576D2T-005G	MC33167D2TR4G
LM2576D2T-15G	MC33167D2TR4G



LM2576D2T-ADJG	MC33167D2TR4G
LM2576D2T-ADJR4G	MC33167D2TR4G
LM2576D2TR4-012G	MC33167D2TR4G
LM2576D2TR4-3.3G	MC33167D2TR4G
LM2576D2TR4-5G	MC33167D2TR4G
LM2595DSADJR4G	MC33167D2TR4G
LM2596DSADJG	MC33167D2TR4G
LM2596DSADJR4G	MC33167D2TR4G
MC33167D2TG	MC33167D2TR4G
MC33167D2TR4G	MC33167D2TR4G
MC34166D2TR4G	MC33167D2TR4G
MC34167D2TG	MC33167D2TR4G
MC34167D2TR4G	MC33167D2TR4G
LM2931ACD2TR4G	NCV59301DS25R4G
LM2931CD2TG	NCV59301DS25R4G
LM2931CD2TR4G	NCV59301DS25R4G
NCP565D2TG	NCV59301DS25R4G
NCP565D2TR4G	NCV59301DS25R4G
NCP5662DS12R4G	NCV59301DS25R4G
NCP5662DS15R4G	NCV59301DS25R4G
NCP5662DS18R4G	NCV59301DS25R4G
NCP5662DS25R4G	NCV59301DS25R4G
NCP5662DS28R4G	NCV59301DS25R4G
NCP5662DS30R4G	NCV59301DS25R4G
NCP5662DS33R4G	NCV59301DS25R4G
NCP5662DSADJR4G	NCV59301DS25R4G
NCP5663DS15R4G	NCV59301DS25R4G
NCP5663DS18G	NCV59301DS25R4G
NCP5663DS18R4G	NCV59301DS25R4G
NCP5663DSADJR4G	NCV59301DS25R4G
NCP57152DSADJR4G	NCV59301DS25R4G
NCP57302DSADJR4G	NCV59301DS25R4G
NCP58302DSADJR4G	NCV59301DS25R4G
NCP59301DS30R4G	NCV59301DS25R4G
NCP59301DS33R4G	NCV59301DS25R4G
NCP59301DS50R4G	NCV59301DS25R4G



初回製品 / プロセス変更通知

文書番号# : IPCN23071X

発行日: 20 May 2020

NCP59302DSADJR4G	NCV59301DS25R4G
NCP630AD2TG	NCV59301DS25R4G
NCP630AD2TR4G	NCV59301DS25R4G
NCP630GD2TG	NCV59301DS25R4G
NCP630GD2TR4G	NCV59301DS25R4G
SCY99302DSADJR4G	NCV59301DS25R4G